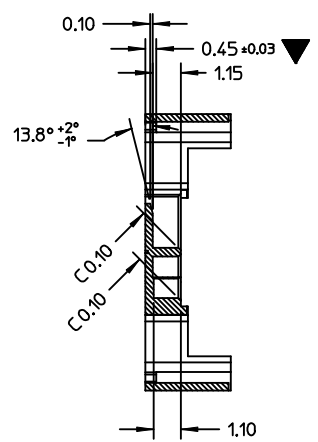
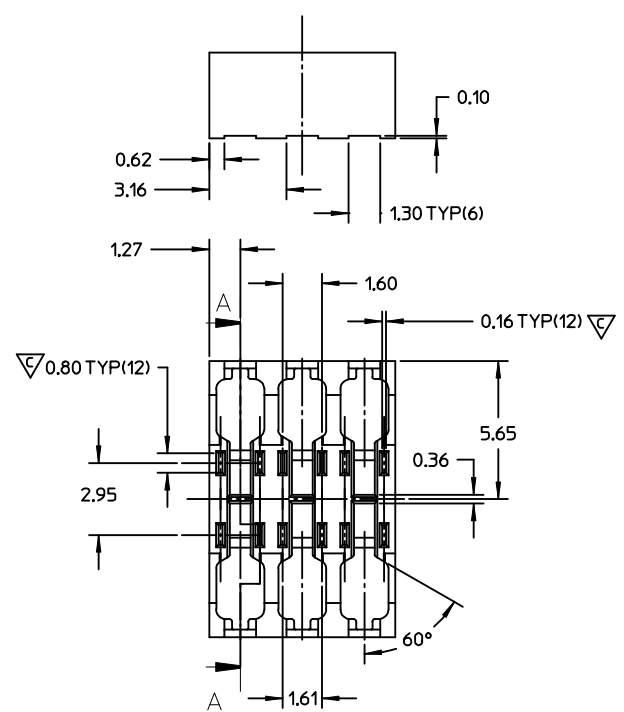
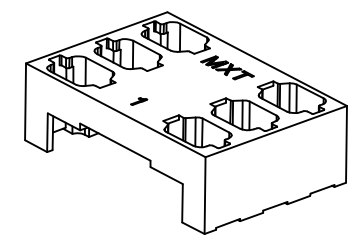
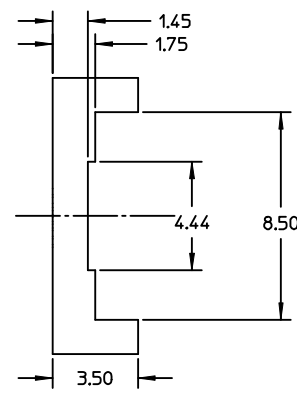
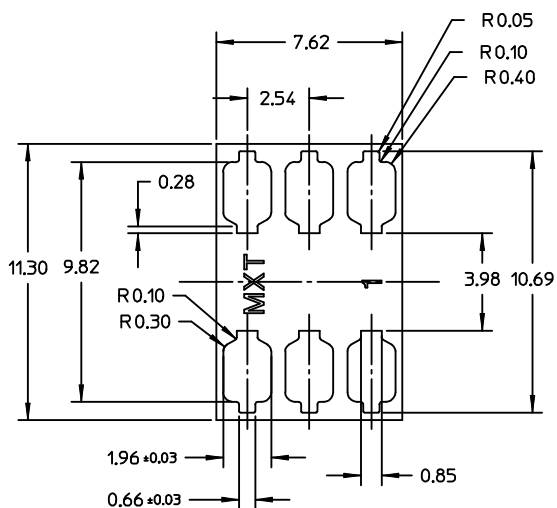


- NOTES:
1. MATERIAL:LCP,30% GLASS FILLED,UL94V-0,COLOR:BLACK PER89992-0393
  2. ALL FLASHES NOT TO EXCEED 0.08MM
  3. BOW IN ALL DIRECTIONS NOT TO EXCEED 0.02MM
  4. ALL UN-DIMENSIONED CORNER MUST BE R0.05MM MAX.
  5. PARTING LINE MISMATCH NOT TO EXCEED 0.05MM MAX.
  6. CAVITY I.D. & LOGO TO BE INTAGLIOED IN A 0.10MM DEEP RECESS

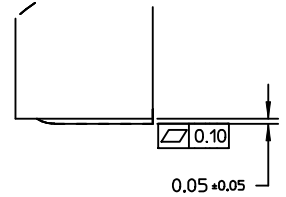
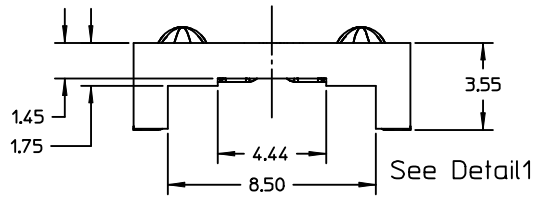
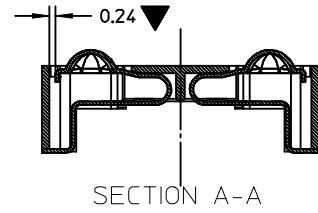
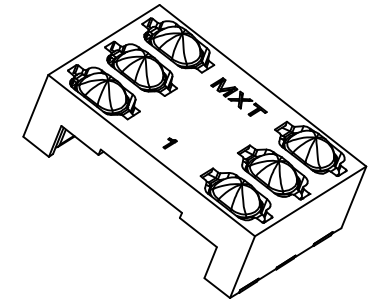
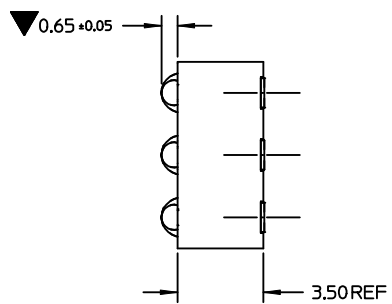
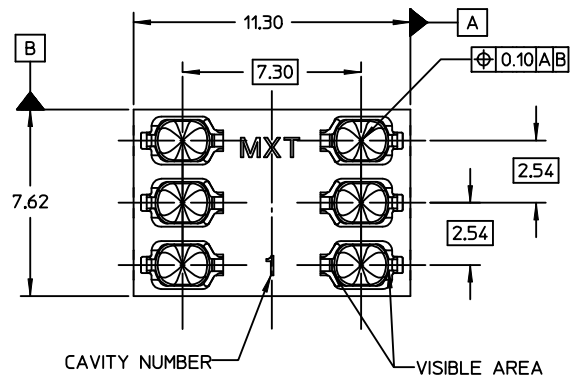
EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR:SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION ▽ = 0 ▽ = 0	mm	INCH	DIMENSION STYLE		TITLE		
		4 PLACES ± ---	± ---	MM ONLY		HOUSING OF 3.50MM HIGH SIMCARD CONNECTOR		
		3 PLACES ± ---	± ---	DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED		
2 PLACES ± 0.05	± ---	CHECKED BY LZHAO	DATE 2003/01/30	MATERIAL NO. ENTER-PART		DOCUMENT NO. E-67687-602	SHEET NO. 1 OF 1	
1 PLACE ± 0.10	± ---	APPROVED BY SAMHUANG 2003/01/30		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								



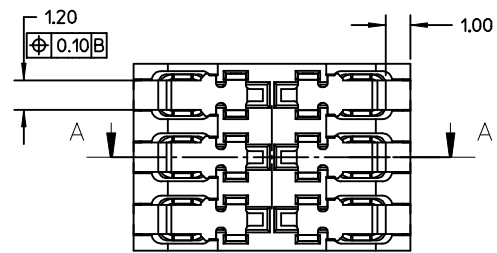
- NOTES:
1. MATERIAL:LCP,30% GLASS FILLED,UL94V-0,COLOR:BLACK PER89992-0393
  2. ALL FLASHES NOT TO EXCEED 0.08MM
  3. BOW IN ALL DIRECTIONS NOT TO EXCEED 0.02MM
  4. ALL UN-DIMENSIONED CORNER MUST BE R0.05MM MAX.
  5. PARTING LINE MISMATCH NOT TO EXCEED 0.05MM MAX.
  6. CAVITY I.D. & LOGO TO BE INTAGLIOED IN A 0.10MM DEEP RECESS

EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR:SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
	DESCRIPTION ▼ = 0 ▽ = 0		mm	INCH	DIMENSION STYLE		TITLE HOUSING OF 3.50MM HIGH SIMCARD CONNECTOR
		4 PLACES	± ---	± ---	MM ONLY		
		3 PLACES	± ---	± ---	DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED MATERIAL NO. ENTER-PART E-67687-602 DOCUMENT NO. E-67687-602 SHEET NO. 1 OF 1
2 PLACES	± 0.05	± ---	CHECKED BY LZHAO	DATE 2003/01/30			
1 PLACE	± 0.10	± ---	APPROVED BY SAMHUANG	DATE 2003/01/30			
		ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

PART NAME	DRAWING NUMBER	PART NUMBER
HOUSING	E-67687-602	676873502
TERMINAL	E-67687-604	676873504



Detail1

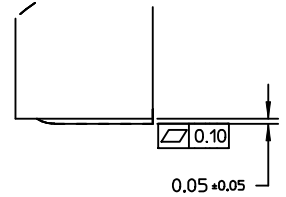
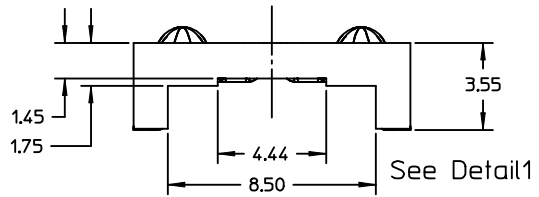
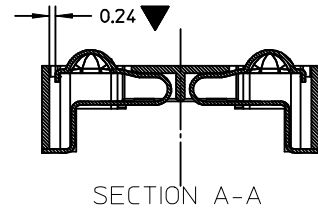
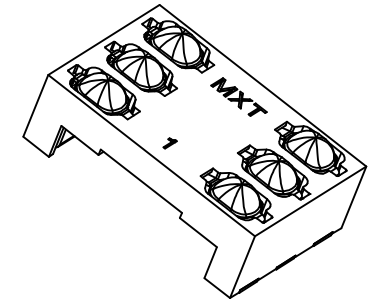
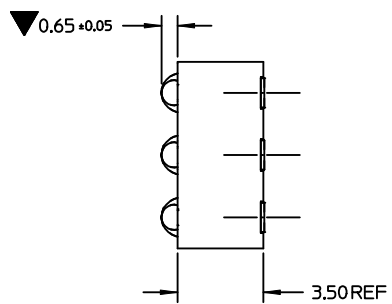
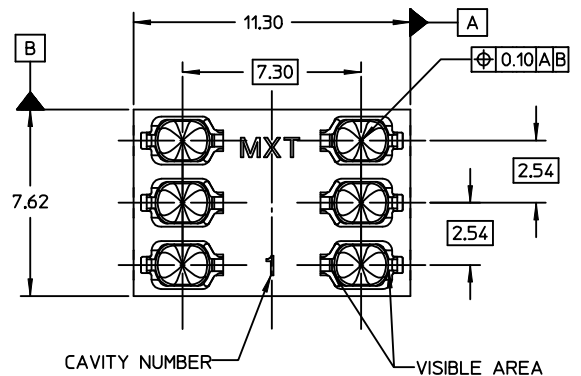


NOTES:

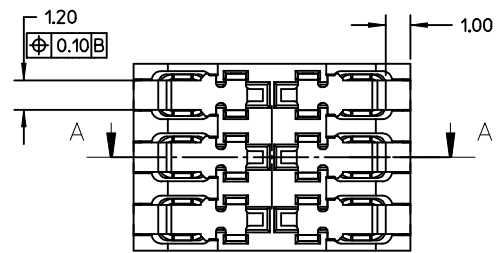
- 1 MATERIAL:  
HOUSING: LCP, 30% GLASS FILLED, UL94V-0, BLACK  
TERMINAL: PHOSPHOR BRONZE C5210, FULL HARD, THICKNESS : 0.15MM
- 2. PLATING:  
SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING  
PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING  
VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING
- 3. PACKAGING: TAPE REEL
- 4. PRODUCT SPECIFICATION REFER TO PS-67687-002

EC NO: SH2003-0029 DRWN: SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION ▽ - 0 C - 0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE	
		4 PLACES ± --- ± ---		DRAWN BY SSUN	DATE 2003/01/30	ASSEMBLY OF SIM CARD CONNECTOR  MOLEX INCORPORATED	
		3 PLACES ± --- ± ---		CHECKED BY LZHAO	DATE 2003/01/30		
2 PLACES ± 0.05 ± ---		APPROVED BY SAMHUANG	DATE 2003/01/30	MATERIAL NO. 676873501	DOCUMENT NO. E-67687-603	SHEET NO. 1 OF 1	
A	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				B

PART NAME	DRAWING NUMBER	PART NUMBER
HOUSING	E-67687-602	676873502
TERMINAL	E-67687-604	676873504



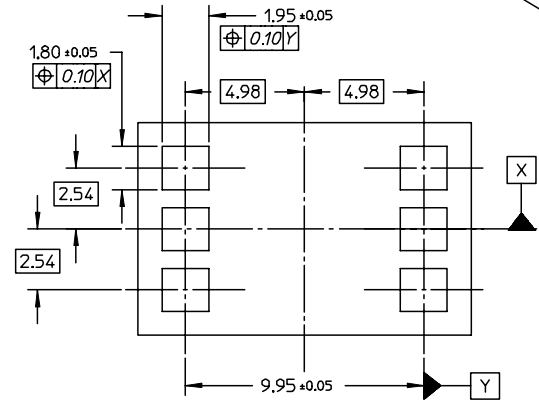
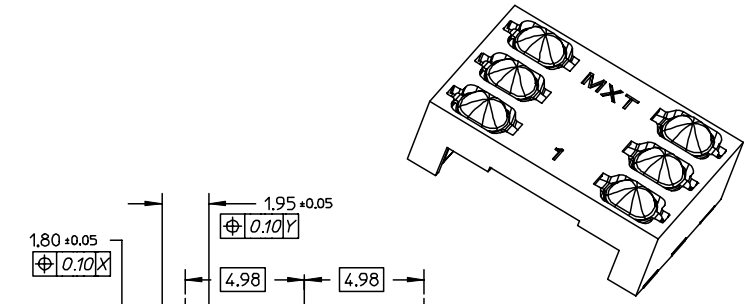
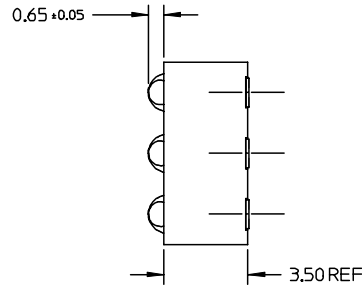
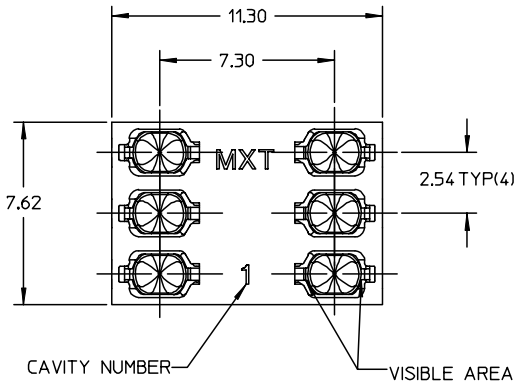
Detail1



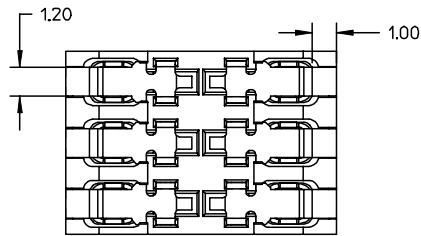
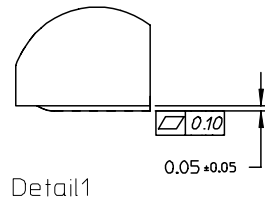
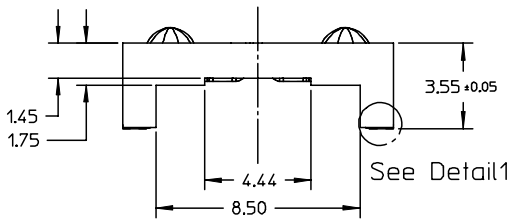
NOTES:

- 1 MATERIAL:  
HOUSING: LCP, 30% GLASS FILLED, UL94V-0, BLACK  
TERMINAL: PHOSPHOR BRONZE C5210, FULL HARD, THICKNESS : 0.15MM
- 2. PLATING:  
SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING  
PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING  
VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING
- 3. PACKAGING: TAPE REEL
- 4. PRODUCT SPECIFICATION REFER TO PS-67687-002

EC NO: SH2003-0029 DRWN: SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY		
	DESCRIPTION ▽ - 0 C - 0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE ASSEMBLY OF SIM CARD CONNECTOR		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY SSUN	DATE 2003/01/30			
		2 PLACES ± 0.05 ± ---	1 PLACE ± 0.10 ± ---	CHECKED BY LZHAO	DATE 2003/01/30			
A	REVISION	ANGULAR ± 2 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY SAMHUANG	DATE 2003/01/30	MATERIAL NO. 676873501	DOCUMENT NO. E-67687-603	SHEET NO. 1 OF 1



RECOMMEND PCB LAYOUT



NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0,BLACK  
 TERMINAL:COPPER ALLOY

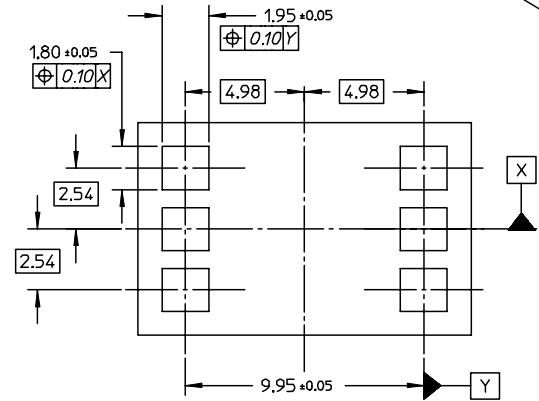
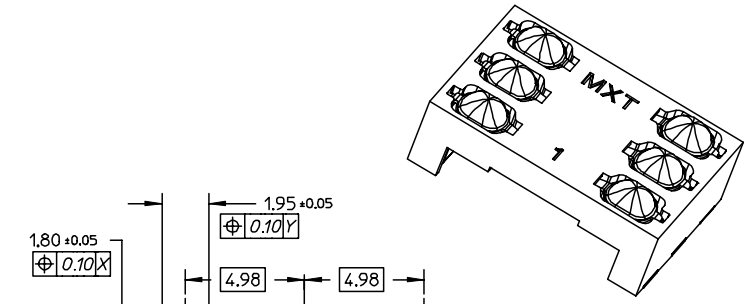
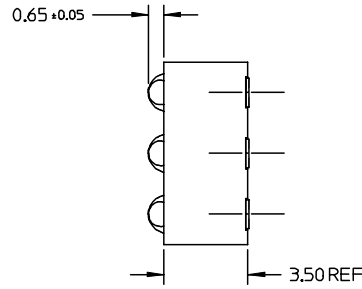
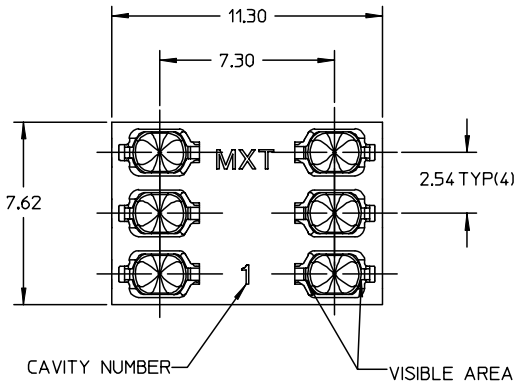
2.PLATING:

SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING  
 PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING  
 VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING

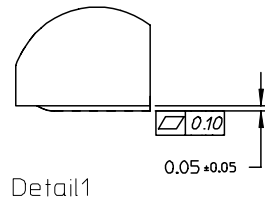
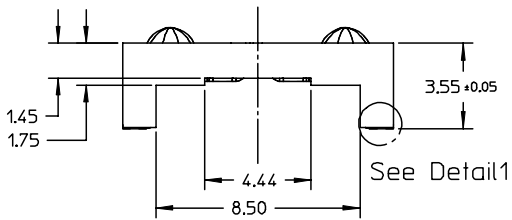
3.PACKAGING: TAPE REEL

4.PRODUCT SPECIFICATION REFER TO PS-67687-002

EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS ▼ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
		mm	INCH	DIMENSION STYLE MM ONLY		TITLE SIM CARD CONNECTOR SALES DRAWING		
		4 PLACES ± --- ± ---		DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED		
		3 PLACES ± --- ± ---		CHECKED BY LZHAO	DATE 2003/01/30	MATERIAL NO. 676873501	DOCUMENT NO. SD-67687-601	SHEET NO. 1 OF 1
A	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



RECOMMEND PCB LAYOUT



NOTES:

1 MATERIAL:

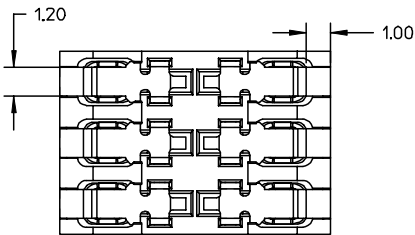
HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0,BLACK  
 TERMINAL:COPPER ALLOY

2.PLATING:

SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING  
 PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING  
 VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING

3.PACKAGING: TAPE REEL

4.PRODUCT SPECIFICATION REFER TO PS-67687-002



EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
		mm	INCH	DIMENSION STYLE MM ONLY		TITLE SIM CARD CONNECTOR SALES DRAWING		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED		
		2 PLACES ± 0.2 ± ---	1 PLACE ± 0.25 ± ---	CHECKED BY LZHAO	DATE 2003/01/30	MATERIAL NO. 676873501	DOCUMENT NO. SD-67687-601	SHEET NO. 1 OF 1
REV A	DESCRIPTION	ANGULAR ± 3 °		DRAFT WHERE APPLICABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		